

Form Type	Distribute	Version	2.0		Ref		IPC 1752A		Sectionals		Manufacturing Info/ Material Info		Subsectionals	D, A
Supplier Information														
Company Name	E TE Connectivi	ty Request Document I	est ment ID			Contact		Penica, John R		Cont	Itact Title Sr		Mgr Environmental Engineering, d Central Eng	
Company Unique ID	TE Connectivi	ty Response I	Response Date		2016-11-08		t Email jrpenic		a@te.com					
Contact Phone	Number	1-717-592-3	266											
						Legal St	atement							
Supplier Acceptance	Supplier true   Acceptance Image: Control of the second se													
Legal Statemer	t													
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.														
	4704500.0	A		450 00404		Pro	duct			Idaa				
Item number	1734592-8	Amount			150.05104						iity			
Manufacturer Item Name	FPC CONN. 0.5MM PITCH B/C, 8P	CONN. Weight Uom M PITCH , 8P		mg		Mfr Site			Auth		ority			
Date		UOM		Each										
EURoHS-0508	i08 Product(s) meets EU RoHS requirement without any exemptions													
ChinaRoHS- 0508 Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information														
EUREACH-1215 REACH Candidate Substances of Very High Concern ARE NOT Contained in the Product Above the Limits per the Definition within REACH														
		Mary Tatal a			Man	ufacturin	g Informa	ation		14/				
Rating		Wave Time				катр к				Additional Info				
Classification Temp		Max Wave Solder Time		20.0		Ramp Down Rate			Psl R Reflo		Rating w			
Max Time Within 5		Psl Rating Wave				Package Designator			Size			0.0		
Time Above 21	7	Reflow Additional I	nfo			Preheat Max Temp			Terr		inal Base	Not Applicable		
Preheat Duration		bulk Solder	bulk Solder		Not Applicable		Nbr or Reflow Cvcles		Tern Plati		ninal ng	Not Applicable		
Preheat Min		Nbr of	0		Compor		nent		:		ipe No		ot Applicable	
Temp		Instances				Product C	pike Disclosur	<u> </u>						
Sub- Item/Material/ Substance	Level	Name	Substance S Category C		Substa CAS	Substance CAS		ce tration	Quantity		Mass per Unit		UOM	Exemption
Material	1	CONTACT - PHOSPHOR BRONZE / C5191R-H							1.0		56.0		mg	
Substance	2	Tin	Supp	Supplier		7440-31-5		5.55			3.108		mg	
Substance	2	Copper	Supplier		7440-50-8		94.15		1.0		52.724		mg	
Substance	2	Phosphorus	Supplier		7723-14-0		0.2		1.0		0.112		mg	
Substance	2	Nickel	Nicke	Nickel		7440-02-0		0.1			0.056		mg	
Material	1	ACTUATOR - PA6T ARLEN E440N Cream							1.0		34.0		mg	
Substance	2	Antimony oxide (Sb2O3)	Supplier		1309-64-4		2.0		1.0		0.68		mg	
Substance	2	Fatty acids, C18-unsatd., dimers, polymers with ethylenediamin e, hexamethylene diamine and propionic acid	Supplier		67989-30-4		53.0		1.0		18.02		mg	
Substance	2	Glass, oxide,	Supplier		65997-17-3		45.0		1.0		15.3		mg	
Material	1	HOLD DOWN- Tin Plating						1.0			0.0265		mg	
Substance	2	Tin	Supp	lier	7440-3	1-5	99.9001	1.0			0.02647353		mg	
Substance	2	Lead	Lead/Lead Compounds		7439-92-1		0.0999	1.0			2.64735E-5		mg	

Material	1	CONTACT- GOLD PLATING				1.0	0.00224	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2- 1212	0.3	1.0	1.0E-5	mg	
Substance	2	Gold	Supplier	7440-57-5	99.7	1.0	0.00223328	mg	
Material	1	HOLD DOWN - PHOSPHOR BRONZE / C5191R-H				1.0	10.0	mg	
Substance	2	Copper	Supplier	7440-50-8	94.45	1.0	9.445	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.2	1.0	0.02	mg	
Substance	2	Tin	Supplier	7440-31-5	5.35	1.0	0.535	mg	
Material	1	HOUSING - LCP E473i Cream				1.0	50.0	mg	
Substance	2	Glass, oxide, chemicals	Supplier	65997-17-3	33.0	1.0	16.5	mg	
Substance	2	1,4- Benzenedicarb oxylic acid, polymer with [1,1-biphenyl]- 4,4-diol, 4- hydroxy/benzoi c acid, 6- hydroxy-2- naphthalenecar boxylic acid and N-(4- hydroxyphenyl) acetamide	Supplier	147310-94-9	67.0	1.0	33.5	mg	
Material	1	CONTACT - NICKEL PLATING				1.0	0.0014	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	1.0E-5	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.9	1.0	0.0013986	mg	
Material	1	HOLD DOWN- NICKEL PLATING				1.0	0.0017	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	1.0E-5	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.9	1.0	0.0016983	mg	